

PXN20 Product Brief

32-bit Power Architecture® Dual Core Microcontrollers for Industrial Networking

The PXN20 products are compatible 32-bit microcontrollers built on Power Architecture® technology. This document describes the available features, and highlights important characteristics of the devices.

The PXN20 products are designed to address the need for single chip industrial networking applications and are tailored to address the need for high performance and high memory size while keeping the power consumption low. Their core and bus architecture offer high performance processing optimized for managing intensive data exchanges between different types of communication protocols. It capitalizes on the available development infrastructure of current Power Architecture® devices and will be supported with software drivers and an operating system to assist with users implementations.

The PXN20 devices have two levels of memory hierarchy, a 32 KB unified cache, and 2 MB of internal flash. The PXN20 has 592 KB on-chip L2 SRAM and

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Application Examples

the PXN21 has 128 KB on-chip L2 SRAM. Refer to [Table 1](#) for specific memory and feature sets of the family members.

1 Application Examples

The PXN20 can be used for a variety of communication applications, such as industrial gateways and process control.

2 Features

This section describes the features of the PXN20 devices.

2.1 PXN20 Features

[Table 1](#) provides a summary of the different members of the PXN20 family and their features.

Table 1. PXN20 Family Feature Set

Feature	PXN20	PXN21
Central Processing Unit (CPU)	e200z650	e200z650
Cache	32K, 4/8way	32K, 4/8way
Floating Point Unit (FPU)	Yes	Yes
Signal Processing Engine (SPE)	Yes	Yes
Memory Management Unit (MMU)	32 entry	32 entry
CPU Execution Speed	Static, 116 MHz	Static, 116 MHz
Input/Output Processor (IOP)	e200z0	e200z0
IOP Execution Speed	1/2 CPU execution speed	1/2 CPU execution speed
Flash with ECC	2 MB	2 MB
Data Flash Block	8x16 KB	8x16 KB
RAM with ECC	592 KB	128 KB
Memory Protection Unit (MPU)	No	16 entry
Direct Memory Access Unit (eDMA)	16 Channel	32 Channel
Ethernet (FEC)	Yes	No
MediaLB (MLB-DIM)	Yes	No
FlexRay Controller	Yes (128 Message Buffers)	No
Analog-to-Digital Converter (ADC)	36 internal channels, 10-bit Supports 32 external channels	64 internal channels, 10-bit Supports 32 external channels
Total Timer I/O (eMIOS200)	24 channels, 16-bit	32 channels, 16-bit
Cross Trigger Unit (CTU)	No	Yes
Asynchronous Serial Interfaces (UART)	6	12
Synchronous Serial Interfaces (SPI)	4	4

Table 1. PXN20 Family Feature Set

Feature	PXN20	PXN21
Controller Area Network (CAN) Controller	6	5
Inter-Integrated Circuit (I ² C) Controller	4	4
Frequency Modulated PLL (FMPLL)	Yes	Yes
4 – 40 MHz XTAL Oscillator	Yes	Yes
16 MHz IRC Oscillator	Yes	Yes
32 kHz XTAL Oscillator	Yes	Yes
128 kHz IRC Oscillator	Yes	Yes
Real Time Counter/ Autonomous Periodic Interrupts (RTC/API)	Yes	Yes
Periodic Interrupt Timer (PIT)	8	8
System Timer Module (STM)	Yes	Yes
Software Watchdog Timer (SWT)	Yes	Yes
General-Purpose I/O (GPIO)	155	155
Clock Monitor (FMPLL)	Yes	Yes
JTAG	Yes	Yes
Nexus Debug (Only supported on emulation package)	Nexus3 (e200Z6) Nexus2+ (e200Z0)	Nexus3 (e200Z6) Nexus2+ (e200Z0)
Production Package	208 MAPBGA	208 MAPBGA
Emulation Package (for development use only)	256 MAPBGA	256 MAPBGA

2.2 PXN20 Block Diagram

Figure 1 shows a top-level block diagram of the PXN20 microcontrollers.

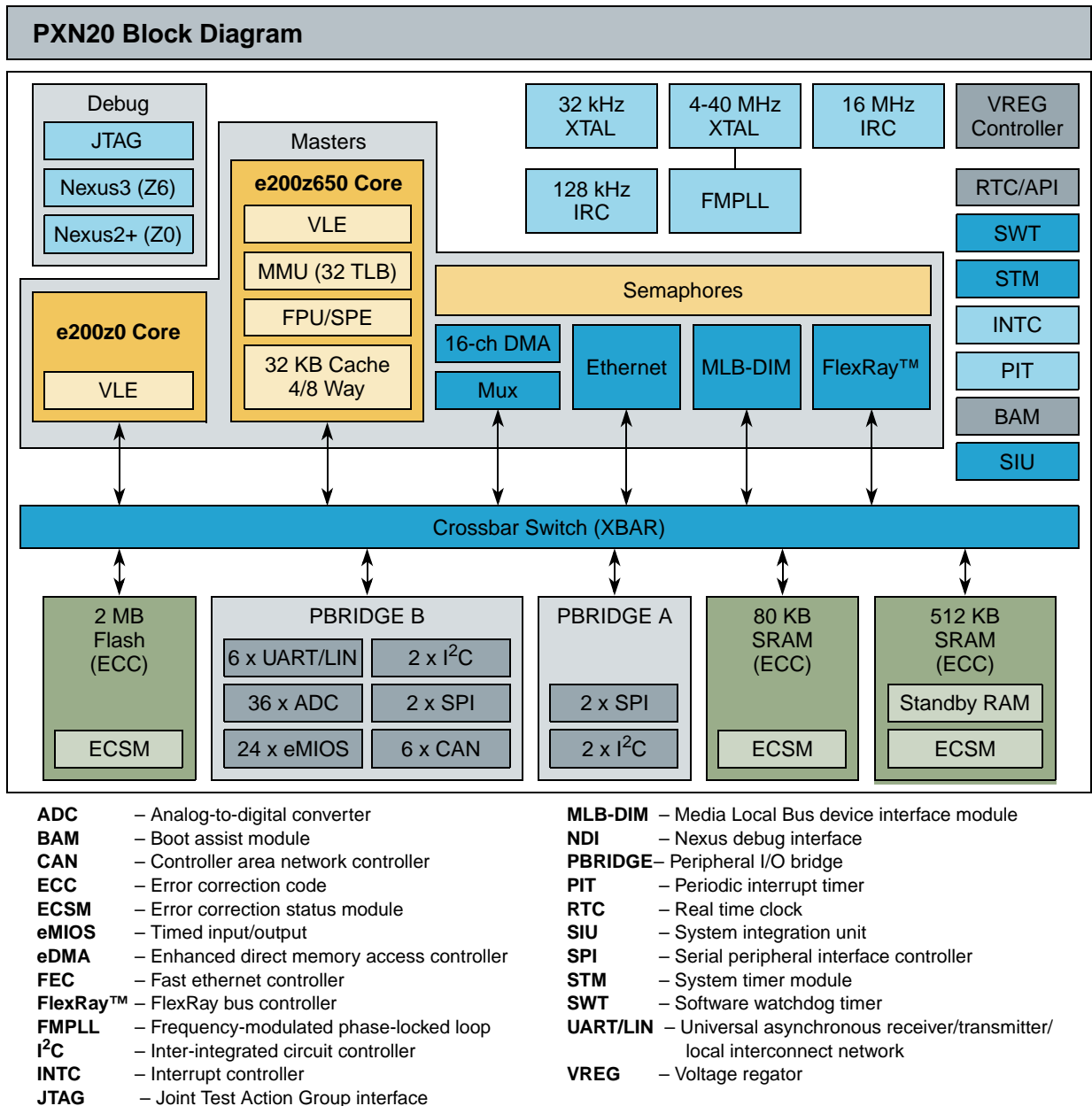


Figure 1. PXN20 Block Diagram

2.3 PXN21 Block Diagram

Figure 2 shows a top-level block diagram of the PXN21.

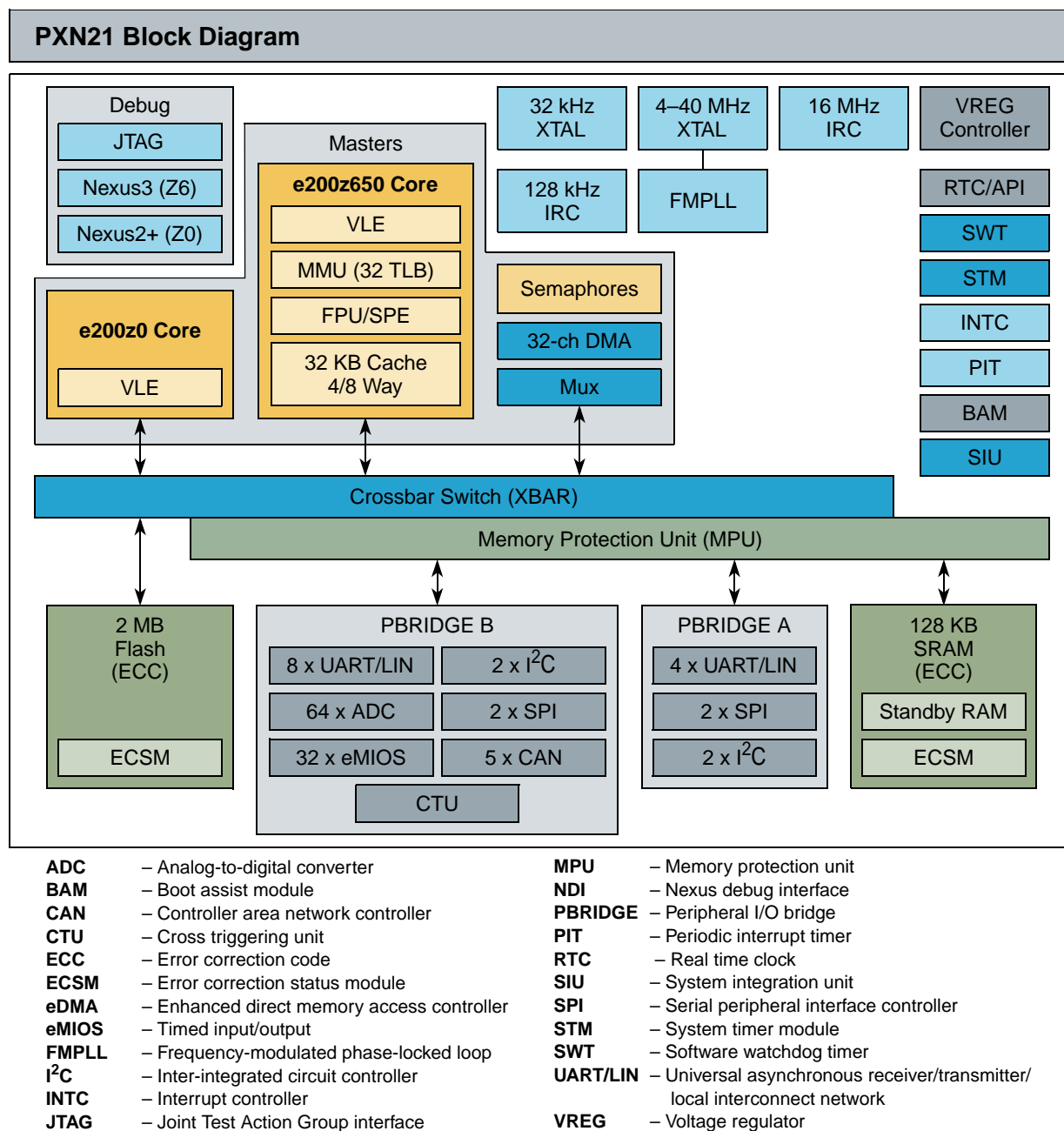


Figure 2. PXN21 Block Diagram

2.4 Critical Performance Parameters

The critical performance parameters of the PXN20 devices feature the following:

- Fully static design operation up to a maximum of 116 MHz, based on 105 °C ambient

Features

- Temperature range -40° to 105° C ambient temperature
- Low power design
 - Designed for dynamic power management of core and peripherals
 - Software-controlled clock gating of peripherals
 - Simple power domains to minimize leakage in low power modes
 - Internal voltage regulator (VREG) enables operation with a single input voltage
 - 3.3 V / 5 V supply (nominal)
 - External Ballast control
- ADC analog supply range 3.0 V – 5.5 V
- Low voltage detect circuit implemented
- Configurable pins
 - Selectable pull-up, pull-down, or no pull on all GPIO pins
 - Selectable open-drain pin

2.4.1 Low Power Operation

The PXN20 devices have one dynamic power mode and one static power mode:

- Low-power modes use clock gating to halt the clock for all or part of the device
- The lowest power mode also uses power gating to automatically turn off the power supply to parts of the device to minimize leakage
- Dynamic power mode: RUN
 - RUN mode is the main operating mode where the entire device is powered and clocked and where most processing activity is done
- Static power mode: SLEEP
 - SLEEP mode halts the clock to the entire device and turns off the power to the majority of the chip in order to offer the lowest power consumption mode of the PXN20. In SLEEP mode the contents of the cores, on-chip peripheral registers and part of the volatile memory are not held. The device can be awakened from up to 32 I/O pins, a reset, or from an internal periodic wake-up. It is also possible to enable the 16 MHz IRC, the 4–40 MHz XTAL, 128 kHz IRC and the 32 kHz XTAL.
 - SLEEP1 mode retains 32 KB of the on-chip RAM
 - SLEEP2 mode retains the 64 KB of the on-chip RAM
 - SLEEP3 mode retains 128 KB of the on-chip RAM
 - Fast wake-up using the on-chip 16 MHz IRC allows rapid execution from RAM on exit from low power modes
 - In SLEEP mode, a 4 – 40 MHz XTAL can be enabled to continue to run
 - In SLEEP mode, the 16 MHz IRC can be enabled to continue to run and may be selected to clock the RTC and API
 - In SLEEP mode, the 128 kHz IRC can be enabled to run and may be selected to clock the RTC and API

- In Sleep mode the 32 kHz XTAL can be enabled to run and may be selected to clock the RTC and API
- Up to 32 external pins for wake-up from low power modes
- Input filters available on all wake-up pins to minimize false wakeups due to noise
- Rapid exit from low power mode with fast startup internal voltage regulator

2.5 Packages

PXN20 family members are offered in the following package types:

- 208-ball MAPBGA, 1mm ball pitch, 17mm × 17mm outline for production
- 256-ball MAPBGA 1mm ball pitch 17mm × 17mm outline for emulation, providing access to full Nexus port without sacrificing GPIO functionality (not available for production)

2.6 Module Features

The following sections provide details of the modules implemented on the PXN20 family.

2.6.1 High Performance e200z650 Core Processor (CPU)

32-bit CPU built on Power Architecture[®] technology

- Freescale Variable Length Encoding (VLE) enhancements for code size footprint reduction
- Thirty-two 64-bit general-purpose registers (GPRs)
- Memory management unit (MMU) with 32-entry fully-associative translation look-aside buffer (TLB)
- Branch processing unit
- Fully pipelined load/store unit
- 32 KB unified cache with line locking
 - 4/8-way set associative
 - Two 32-bit fetches per clock
 - Eight-entry store buffer
 - Way locking
 - Supports assigning cache as instruction or data only on a per way basis
 - Supports tag and data parity
- Vectored interrupt support
- Very low interrupt latency
- Reservation instructions for implementing read-modify-write constructs (internal SRAM and flash)
- Signal processing engine (SPE) auxiliary processing unit (APU) operating on 64-bit general purpose registers
- Floating point

Features

- IEEE[®] 754 compatible with software wrapper
- Single precision in hardware; double precision with software library
- Conversion instructions between single precision floating point and fixed point
- Wait instruction
- Extensive system development support through Nexus debug module

2.6.2 I/O Processor High Performance e200z0 Core (IOP)

The IOP supports the following features:

- High performance, low cost e200z0 core processor for managing peripherals and interrupts
- Single issue 4-stage pipelined in-order execution, 32-bit Power Architecture[®] CPU
- Variable length encoding (VLE), allowing mixed 16-bit and 32-bit instructions
 - Results in efficient code size footprint
 - Minimizes impact on performance
- Branch processing acceleration using lookahead instruction buffer
- Load/store unit
 - 1-cycle load latency
 - Misaligned access support
 - No load-to-use pipeline bubbles
- Thirty-two 32-bit general purpose registers (GPRs)
- Hardware vectored interrupt support
- Reservation instructions for implementing read-modify-write constructs
- Multi-cycle divide (divw) and load multiple (lmw) store multiple (smw) multiple class instructions, can be interrupted to prevent increases in interrupt latency
- Extensive system development support through Nexus debug port

2.6.3 On-Chip Flash

On-chip flash on the PXN20 devices features the following:

- 2 MB burst flash memory
 - Flash partitioning: 4 × 16 KB; 4 × 16 KB; 2 × 64 KB; 2 × 128 KB; 6 × 256 KB
 - 16 KB shadow flash blocks
 - Typical flash access time: 0 wait-state for buffer hits, 3 wait-states for page buffer miss at 116 MHz
 - 64-bit ECC with single-bit correction, double-bit detection for data integrity
- Dual flash ports to minimize access contention between main core and IOP
 - Each port supported with separate page buffers
- Flash page buffers to improve access time to code and data held in flash
 - 4 × 128-bit page buffers with programmable prefetch control for flash access

- Page buffers can be allocated for code-only, fixed partitions of code and data, all available for any access
- Censorship protection scheme to prevent flash content visibility
- EE emulation supported by small 16 KB flash blocks in main array with multiple read while write partitions
- Hardware managed flash writes, erase and verify sequence
- Supports flash writes using internal 16 MHz RC oscillator
- Flash partitioning:

Table 2. Flash Partitioning

	PXN20
	2 MB
Flash_Base + 0x0000_0000	16 KB
Flash_Base + 0x0000_4000	16 KB
Flash_Base + 0x0000_8000	16 KB
Flash_Base + 0x0000_C000	16 KB
Flash_Base + 0x0001_0000	16 KB
Flash_Base + 0x0001_4000	16 KB
Flash_Base + 0x0001_8000	16 KB
Flash_Base + 0x0001_C000	16 KB
Flash_Base + 0x0002_0000	64 KB
Flash_Base + 0x0003_0000	64 KB
Flash_Base + 0x0004_0000	128 KB
Flash_Base + 0x0006_0000	128 KB
Flash_Base + 0x0008_0000	256 KB
Flash_Base + 0x000C_0000	256 KB
Flash_Base + 0x0010_0000	256 KB
Flash_Base + 0x0014_0000	256 KB
Flash_Base + 0x0018_0000	256 KB
Flash_Base + 0x001C_0000	256 KB
Shadow Block	16 KB

- Error correction status
 - Configurable error-correcting codes (ECC) reporting for RAM and flash

2.6.4 On-Chip SRAM

On-chip SRAM on the PXN20 family features the following:

- Up to 592/128 KB general purpose RAM

Features

- Two RAM blocks implemented on separate crossbar ports to reduce arbitration events for high access master to on-chip RAM.
 - One port with 80 KB (PXN20 only)
 - One port with 512/128 KB RAM
- Typical SRAM access time: 0 wait-state for reads and 32-bit writes; 1 wait-state for 8- and 16-bit writes if back to back with a read to same memory block
- 32-bit ECC with single-bit correction, double bit detection for data integrity
- Supports byte (8-bit), half word (16-bit), and word (32-bit) writes for optimal use of memory
- User transparent ECC encoding and decoding for byte, half word, and word accesses

2.6.5 On-Chip Voltage Regulator (VREG)

The on-chip voltage regulator includes the following features:

- Single supply device
- 3.3 V / 5 V (nominal) input supply voltage supported
- Supports I/O levels independent of main supply
 - MLB has separate supply pins to support down to 2.5 V (nominal) operation
 - Multiple I/O domains with separate supply pins
- Low voltage detectors (LVD) supported on internal supplies
- Cold crank operation supported without triggering LVDs

2.6.6 Fast Ethernet Controller (FEC)

The FEC incorporates the following features

- Support for 3 different physical interfaces
 - 100 Mbps IEEE 802.3 MII
 - 10 Mbps IEEE 802.3 MII
 - 10 Mbps 7-wire interface (industry standard)
- Built in FIFO and DMA controller
- IEEE 802.3 MAC (compliant with IEEE 802.3 1998 edition)
- Programmable max frame length supports IEEE 802.1 VLAN tags and priority
- IEEE 802.3 full duplex flow control
- Support for full duplex operation (200 Mbps throughput) with a system clock of 100 MHz using the external TX_CLK or RX_CLK
- Support for full duplex operation(100 Mbps throughput) with a system clock of 50 MHz using the external TX_CLK or RX_CLK
- Retransmission from transmit FIFO following a collision (no system bus utilization)
- Automatic internal flushing of the receive FIFO for runts (collision fragments) and address recognition rejects (no system bus utilization)

- Address recognition
- RMON and IEEE statistics
- Interrupts for network activity and error conditions

2.6.7 Analog to Digital Converter Module (ADC)

The PXN20 ADC features the following:

- 10-bit A/D resolution
- $0-V_{DD}$ common mode conversion range
- Supports conversions speeds of up to 1 μ s
- Internally multiplexed channels
 - 10-bit ± 2 least significant bits (LSB) accuracy (TUE) available for 16 channels
 - 10-bit ± 3 LSB accuracy (TUE) available for remaining channels
 - Dedicated result register available for every internally muxed channel
- Externally multiplexed channels
 - Internal control to support generation of external analog multiplexor selection
 - Four internal channels optionally used to support externally multiplex inputs, providing transparent control for additional ADC channels
 - Each of the four channels supports up to 8 externally muxed inputs
- Three independently configurable sample and conversion times for high occurrence channels, internally muxed channels and externally muxed channels
- Right-aligned result format
- Support for one-shot, scan and injection conversion modes
- Traceability of each channels with conversion result.
- Injection mode status bit implemented on adjacent 16-bit register for each result
- Independently configurable parameters for channels:
 - Offset refresh
 - Sampling
- Cross Triggering support (PXN21 only)
 - Internal conversion triggering from periodic interrupt timer (PIT) or timed I/O module (eMIOS200) via Cross Triggering Unit (CTU)
 - One input pin configurable as external conversion trigger source
- Four configurable analog comparator channels offering range comparison with triggered alarm
- Supports operation of ADC using internal 16 MHz RC oscillator
- All unused analog pins available as general purpose input pins
- Selected unused analog pins available as general purpose output pins
- Power-down mode
- Supports for DMA transfer of results

2.6.8 Cross Triggering Unit (CTU)

The CTU features the following:

- Collection of 9 bit timers with an exponential prescaler able to generate the trigger event for ADC conversions
- 9-bit down counters counting from a programmable start value to 0
- Different counters associated with different channel groups
- Channel group is defined based on PWM channel clock
- Different delay value for each eMIOS flag/PIT event
- 4-bit programmable exponential prescaler
- Single cycle delayed trigger output. Trigger output is a combination of 64 input flags/events connected to different timers in the system
- Maskable interrupt generation whenever a trigger output is generated
- Event configuration registers dedicated to UC flag/triggering event
- Acknowledgement signal to eMIOS for clearing the flag
- Synchronization with ADC to avoid collision

2.6.9 Serial Communication Interface Module (UART)

The PXN20 devices include up to two UART modules and support UART Master mode, UART Slave mode and UART mode. The modules are UART state machine compliant to the UART 1.3 and 2.0 and 2.1 Specifications and handle UART frame transmission and reception without CPU intervention.

The serial communication interface module offers the following:

- UART features:
 - Full-duplex operation
 - Standard non return-to-zero (NRZ) mark/space format
 - Data buffers with 4-byte receive, 4-byte transmit
 - Configurable word length (8-bit or 9-bit words)
 - Error detection and flagging
 - Parity, noise and framing errors
 - Interrupt driven operation with 4 interrupts sources
 - Separate transmitter and receiver CPU interrupt sources
 - 16-bit programmable baud-rate modulus counter and 16-bit fractional
 - 2 receiver wake-up methods
- LIN features:
 - Autonomous LIN frame handling
 - Message buffer to store identifier and up to eight data bytes
 - Supports message length of up to 64 bytes
 - Detection and flagging of LIN errors

- Sync field; Delimiter; ID parity; Bit, Framing; Checksum and Timeout errors
- Classic or extended checksum calculation
- Configurable Break duration of up to 36-bit times
- Programmable Baud rate prescalers (13-bit mantissa, 4-bit fractional)
- Diagnostic features
 - Loop back
 - Self Test
 - LIN bus stuck dominant detection
- Interrupt driven operation with 16 interrupt sources
- LIN slave mode features
 - Autonomous LIN header handling
 - Autonomous LIN response handling
 - Discarding of irrelevant LIN responses using up to 16 ID filters

2.6.10 Controller Area Network Module (CAN)

The enhanced CAN module features the following:

- Compliant with CAN protocol specification, Version 2.0B active
- 64 mailboxes, each configurable as transmit or receive
 - Mailboxes configurable while module remains synchronised to CAN bus
- Transmit features
 - Arbitration scheme according to message ID, message buffer number or local priority
 - Internal arbitration to guarantee no inner priority inversion
 - Multiple transmit buffers to avoid outer priority inversion
 - Transmit abort procedure and notification
- Receive features
 - Individual programmable filters for each mailbox
 - Hardware FIFO can be enabled
 - 8 mailboxes can be configured to provide a 6-entry receive FIFO and 8 programmable acceptance filters
- Programmable clock source
 - System clock
 - Direct oscillator clock to avoid PLL jitter
 - Listen only mode capabilities

2.6.11 Inter-IC Communications Module (I²C)

The I²C module features the following:

- Two-wire bi-directional serial bus for on-board communications

Features

- Compatibility with I²C bus standard
- Multimaster operation
- Software-programmable for one of 256 different serial clock frequencies
- Software-selectable acknowledge bit
- Interrupt-driven, byte-by-byte data transfer
- Arbitration-lost interrupt with automatic mode switching from master to slave
- Calling address identification interrupt
- Start and stop signal generation/detection
- Repeated START signal generation
- Acknowledge bit generation/detection
- Bus-busy detection

2.6.12 Serial Peripheral Interface Module (SPI)

The PXN20 SPI features the following:

- Full duplex, synchronous transfers
- Master or slave operation
- Programmable master bit rates
- Programmable clock polarity and phase
- End-of-transmission interrupt flag
- Programmable transfer baud rate
- Programmable data frames from 4 to 16 bits
- Up to 24 chip select lines available (6 per SPI module); the number available at any time is dependent on package and pin multiplexing.
- Up to 4 independently configurable transfer types can be configured for each SPI using the clock and transfer attributes registers
- Chip select strobe available as alternate function on one of the chip select pins for de-glitching
- FIFOs for buffering up to 4 transfers on the transmit and receive side
- General purpose I/O functionality on pins when not used for SPI
- Queueing operation possible through use of eDMA
- Serialization of selected sources (eMIOS channels and Phantom ports in SIU)

2.6.13 Enhanced Modular Input Output System (Timers - eMIOS200)

The PXN20 family implement a scaled-down version of the eMIOS module:

- Supports timed I/O channels with 16-bit counter resolution
- Buffered updates
- Support for shifted PWM outputs to minimize occurrence of concurrent edges

- Supports configurable trigger outputs for ADC conversions for synchronization to channel output waveforms
- Edge aligned output pulse width modulation
 - Programmable pulse period and duty cycle
 - Supports 0% and 100% duty cycle
 - Shared or independent time bases
- Up to 32¹ single action channels offering input capture and output compare functions
- Up to 32¹ dual action channels offering output pulse width modulation,
- Up to 13¹ output pulse width and frequency modulation and center aligned output PWM channels with dead time.
- Up to 5¹ modulus up/down counters that can be used to drive counter buses.
- DMA transfer support available

2.6.14 Periodic Interrupt Timer Module (PIT)

The PIT features the following:

- Up to 8 general purpose interrupt timers
- Up to 2 interrupt timers for triggering ADC conversions
- 32-bit counter resolution
- Clocked by system clock frequency

2.6.15 System Timer Module (STM)

One STM supporting

- One 32-bit up counter with 8-bit prescaler
- Four 32-bit compare channels running off the same up-counter
- Independent interrupt source for each channel
- Clocked by the main system clock
- Instantiated in the same CPU clock domain
- Counter can be stopped in debug mode

2.6.16 Enhanced Direct Memory Access Controller (eDMA)

The following summarizes the PXN20 implementation of the eDMA controller:

- Support independent 8, 16 or 32 bit single value or block transfers
- Supports variable sized queues and circular queues
- Source and destination address registers are independently configured to post-increment or remain constant
- Each transfer is initiated by a peripheral, CPU, periodic timer interrupt or eDMA channel request

1. Depends on pin muxing and product derivative

Features

- Each eDMA channel can optionally send an interrupt request to the CPU on completion of a single value or block transfer
- DMA transfers possible between system memories, SPIs, I²C, ADC, UART, eMIOS200 and General Purpose I/Os
- Programmable DMA channel mux allows assignment of any DMA source to any available DMA channel with up to a total of 64 potential request sources.

2.6.17 Crossbar Switch (XBAR)

The Crossbar Switch allows concurrent accesses between masters and slaves, and provides these features:

- Up to 6 master ports
 - Masters: Z6 CPU, Z0 CPU, eDMA, FlexRay, FEC, MLB
- Multiple bus slaves to enable access to flash, SRAM ports and peripherals
- Multiple AIPS bridges to support connection to all peripheral modules
- Crossbar supports consecutive transfers from master to available slaves
- 32-bit internal address bus, 32-bit internal data bus
- User configurable priority arbitration based for masters
- Temporary dynamic priority elevation for IOP and DMA

2.6.18 Memory Protection Unit (MPU)

The MPU provides the following features:

- Supports up to 16 region descriptors for per-master protection
- Start and end address defined with 32-byte granularity
- Overlapping regions supported
- Protection attributes can optionally include process ID
- Protection offered for 4 concurrent read ports
- Read and write attributes for all masters
- Execute and supervisor/user mode attributes for processor masters

2.6.19 Interrupt Controller (INTC)

The PXN20 implements an interrupt controller that features the following:

- Unique 9-bit vector for each of the 316 separate interrupt sources (22 reserved)
- 8 software triggerable interrupt sources
- 16 priority levels with fixed hardware arbitration within priority levels for each interrupt source
- Ability to modify the ISR or task priority.
 - Modifying the priority can be used to implement the priority ceiling protocol for accessing shared resources.
- External high priority interrupt directly accessing the main core critical interrupt mechanism

- Interrupt steering between main CPU and IOP
 - Independent selection of any interrupt source to be routed through IOP
 - Interrupts share same priority level between IOP and CPU

2.6.20 System Clocks and Clock Generation

The following list summarizes the system clock and clock generation on the PXN20:

- System clock can be derived from the following sources
 - 4–40 MHz XTAL
 - FMPLL
 - 16 MHz IRC oscillator
- Programmable output clock divider of system clock ($\div 1$, $\div 2$, $\div 4$, $\div 8$, $\div 16$)
- Separate programmable peripheral bus clock divider ratio ($\div 1$, $\div 2$, $\div 4$, $\div 8$) applied to system clock
- Frequency Modulated Phase-locked loop (FMPLL)
 - Input clock frequency from 4 MHz to 40 MHz
 - Clock source from external oscillator
 - Lock detect circuitry continuously monitors lock status
 - Loss of clock (LOC) detection for reference and feedback clocks
 - On-chip loop filter (for improved electromagnetic interference performance and reduces number of external components required)
- On-chip crystal oscillators supporting 4 MHz to 40 MHz crystals
- Dedicated 16 MHz internal RC oscillator
 - 16 MHz internal RC oscillator supports low speed code execution and clocking of peripherals through selection as the system clock
 - Used as default clock source out of reset
 - Provides a clock for rapid start-up from low power modes
 - Provides a clock for Software Watchdog Timer (SWT)
 - Provides a back-up clock in the event of PLL or external oscillator clock failure
 - 5% accuracy over the operating temperature range (after factory trim)
 - Trimming registers to support frequency adjustment with in-application calibration
- Dedicated internal 128 kHz internal RC oscillator for low power mode operation and self wake-up
 - 5% accuracy (after factory trim)
 - Trimming registers to support improve accuracy with in-application calibration
- Dedicated 32 kHz external oscillator for accurate timed wake-up

2.6.21 System Integration Unit (SIU)

The SIU features the following:

- Up to four levels of internal pin multiplexing, allowing exceptional flexibility in the allocation of device functions for each package
- Centralized general purpose input output (GPIO) control of up to 155 input/output pins (package dependent)
- All GPIO pins can be independently configured to support pull-up, pull down, or no pull
- Reading and writing to GPIO supported both as individual pins and 16-bit wide ports
- The majority of the peripheral pins can be alternatively configured as both general purpose input or output pins. The exception is selected precision ADC channels which support alternative configuration as general purpose inputs only.
- Direct readback of the pin value supported on all digital output pins through the SIU
- Configurable digital input filter that can be applied to up to 32 general purpose input pins for noise elimination on external wakeups

2.6.22 Software Watchdog Timer (SWT)

The Watchdog timer on the PXN20 features the following:

- Watchdog enabled out of reset with default 10 ms timeout from internal 16 MHz IRC clock
- Supports normal and windowed mode
- Support for protected access to watchdog control registers with optional soft and hard locks
 - Soft lock allows the lock to be overridden by writing a special software code
 - Hard lock prevents any changes until after a reset, once enabled
- Watchdog supports optional halting during low power modes
- Configurable response on timeout: reset, interrupt, or interrupt followed by reset

2.6.23 Boot Assist Module (BAM)

The BAM is implemented as follows:

- Configures device to support code download via CAN or UART and execution of download routine
- Multiple bootcode starting locations out of reset through implementation of search for valid reset configuration halfword

2.6.24 Dual-Channel FlexRay Controller (FR)

The dual-channel FlexRay controller features the following:

- Full implementation of FlexRay Protocol Specification 2.1, RevA
- Single channel support

- FlexRay Port A can be configured to be connected either to physical FlexRay channel A or physical FlexRay channel B
- FlexRay bus data rates of 10, 8, 5, and 2.5 Mbit/s supported
- Up to 128 configurable message buffers with
 - Individual frame ID filtering
 - Individual channel ID filtering
 - Individual cycle counter filtering
- Message buffer header, status and payload data stored in dedicated FlexRay memory
 - Allows for flexible and efficient message buffer implementation
 - Consistent data access ensured by means of buffer locking scheme
 - Application can lock multiple buffers at the same time
- Message buffers can be configured as:
 - Receive message buffer
 - Single buffered transmit message buffer
 - Double buffered transmit message buffer (combines two single buffered message buffers)
- Individual message buffer reconfiguration supported
- Two independent receive FIFOs
 - One receive FIFO per channel
 - Up to 255 entries for each FIFO
 - Global frame ID filtering, based on both value/mask filters and range filters
 - Global channel ID filtering
 - Global message ID filtering for dynamic segment
- Size of message buffer payload data configurable from 0 up to 254 bytes
- Two independent message buffer segments with configurable size of payload data section
 - Each segment can contain message buffers assigned to the static segment and message buffers assigned to the dynamic segment at the same time
- Support for independent internal clock source provided to module from a separate external 40 MHz crystal
- 1 absolute timer
 - 1 timer that can be configured to absolute or relative

2.6.25 Media Local Bus (MLB)

The following summarizes the MLB configuration:

- Support of 16 logical channels running at a maximum speed of 1024 Fs
- Transmission of commands and data and reception of receive status when functioning as the transmitting device associated with a logical channel address
- Reception of commands and data and transmission as receive status responses when functioning as the receiving device associated with a logical channel address

Features

- System channel command handling
- Internal DMA operation
- Local channel buffer RAM (single port RAM) size of 2048 × 36 bits words
- Support for 3-pin only
- Support for MLB I/O voltage specs 2.5 V (nominal) and 3.3 V (nominal)

2.6.26 Real Time Counter (RTC)

Real Time counter supports wake-up from Low Power modes or real time clock generation

- Configurable resolution for different timeout periods
 - 1 sec resolution for > 1 hour period
 - 1 ms resolution for 2-second period
- Selectable clock sources from:
 - Internal 128 kHz RC oscillator
 - Internal 16 MHz RC oscillator
 - 32 kHz external oscillator
- RTC supports continued operation through reset, count only reset manually, or by power on reset (POR)

2.6.27 JTAG Controller (JTAGC)

The JTAGC is compliant with the IEEE 1149.1-2001 standard and has the following main features:

- IEEE 1149.1-2001 test access port (TAP) interface
- A JCOMP input that provides the ability to share the TAP
- A 5-bit instruction register that supports several IEEE 1149.1-2001 defined instructions, as well as several public and private MCU specific instructions
- Three test data registers: Bypass register, boundary scan register and a device identification register
- Supporting boundary scan testing
- TAP controller state machine

2.6.28 Nexus Development Interface (NDI)

The NDI module is compliant with the IEEE-ISTO 5001-2003 standard. The following features are implemented, but only available on the 256 MAPBGA emulation package:

- 17-bit full duplex pin interface for medium and high visibility throughput
 - Full port mode (12 MDO)
 - Auxiliary input port (MCKO, 12xMDO, 2xMSEO, EVTO, EVTI)
 - Auxiliary output port
 - 5 pin JTAG port (JCOMP, TDI, TDO, TMS and TCK)

The NPC block performs the following functions

- Controls arbitration between e200Z6 and e200Z0 Nexus modules to the Nexus Auxiliary output port
- Generates full port mode indication output port
- Generates MCKO and frequency division (1/2, 1/4, 1/8).
- Controls sharing of EVTO/EVTI
- Enables gating of MCKO when the auxiliary output port is idle.

e200Z6 development support features (Nexus class3)

- IEEE-ISTO 5001-2003 standard class 3 compliant
- Program trace via branch trace messaging (BTM)
- Data trace via data write messaging (DWM) and data read messaging (DRM). This allows the development tools to trace reads and /or writes to selected internal memory resources
- Ownership via ownership trace messaging (OTM). OTM facilitates ownership trace by providing visibility of which process ID or operating system task is activated
- Run-time access to the e200Z6 memory map via the JTAG port
- Watchpoint messaging
- Watchpoint trigger enable of program and/or data trace messaging

e200Z0 development support features (Nexus class 2+)

- IEEE-ISTO 5001-2003 standard class 2 compliant with additional class 3 and 4 features available
- Program trace via branch trace messaging (BTM)
- Ownership via ownership trace messaging (OTM)
 - OTM facilitates ownership trace by providing visibility of which process ID or operating system task is activated
- Run-time access to the e200Z6 memory map via the JTAG port
- Watchpoint messaging
- Watchpoint trigger enable of program and/or data trace messaging

Capability of an event output signal from either core to generate a debug request in the other core

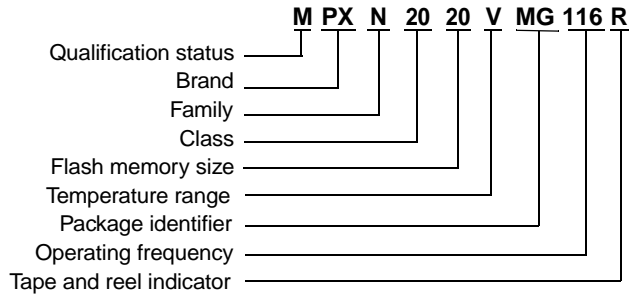
- All Nexus port pins operate at 3.3 V levels
- Nexus supports debug through reset and low power

3 Developer Support

This family of MCUs is supported by Freescale's Tower Development System as well as a broad set of advanced debug and runtime software:

- CodeWarrior
- FreeMaster
- MQX
- RAppID Init
- RAppID Toolbox

4 Orderable Parts



Qualification status

P = Pre-qualification (engineering samples)
 M = Fully spec. qualified, general market flow
 S = Fully spec. qualified, automotive flow

Family

D = Display Graphics
 N = Connectivity/Network
 R = Performance/Real Time Control
 S = Safety

Flash Memory Size

20 = 2 MB

Temperature range

V = -40 °C to 105 °C
 (ambient)

Package identifier

MG = 208 MAPBGA

Operating frequency

116 = 116 MHz

Tape and reel status

R = Tape and reel
 (blank) = Trays

Note: Not all options are available on all devices. See [Table 3](#) for more information.

Table 3. Orderable part number summary

Part number	Flash/SRAM	Package	Speed (MHz)
MPXN2020VMG116	2 MB / 592 KB	208 MAPBGA (17 mm x 17 mm)	116
MPXN2120VMG116	2 MB / 128 KB	208 MAPBGA (17 mm x 17 mm)	116

5 Revision History

Table 4 summarizes revisions to this document

Table 4. Revision History

Revision (Date)	Description
Rev. 1 (06/2011)	Initial release.

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Document Number: PXN20PB
Rev. 1
06/2011

